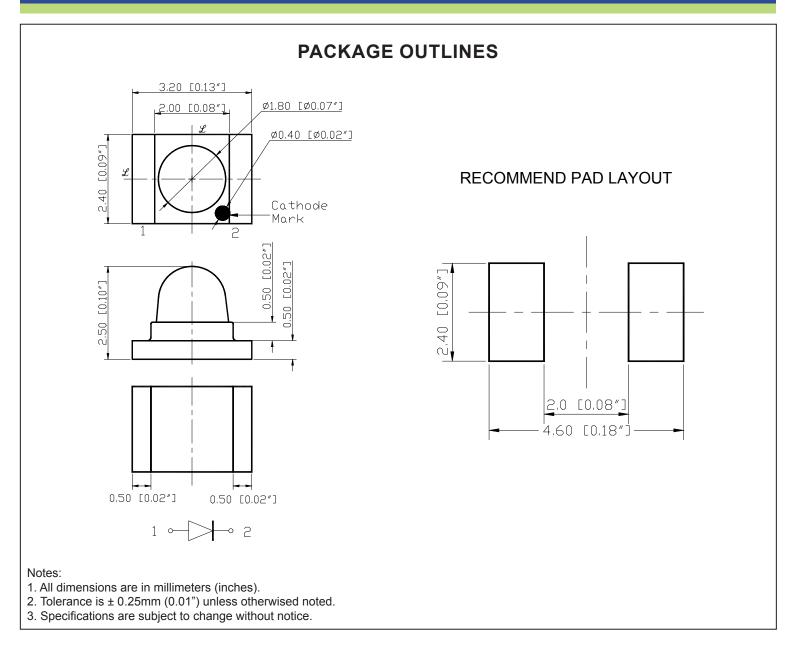


### SPECIFICATION

# CSD131B3C



Part Number	Chip Material	Color of Emission Lens Type		Viewing Angle	
CSD131B3C	InGaN	Blue	Water Clear	15°	





### **ABSOLUTE MAXIMUM RATINGS**

### (TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	lR	10	μA	
Power Dissipation	Pd	111	mW	
Operating Temperature Range	Тор	-40~+85	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lfp	125	mA	
Soldering Temperature	Tsol	Max 260°C for 10 sec Max		

## OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

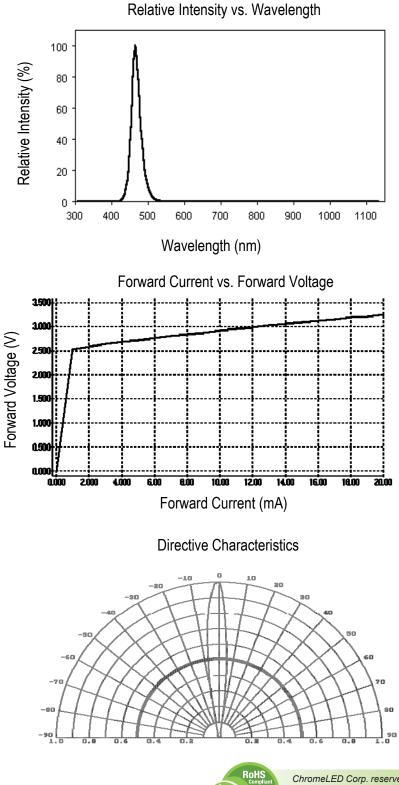
Deremeter	Symbol	Test Condition	Value			Linit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	١v	IF = 20mA	1250	2200	-	mcd
Forward Voltage	Vf	IF = 20mA	-	3.1	3.7	V
Reverse Leakage Current	lr	VR = 5V	-	10	-	μA
Viewing Angle at 50% Iv	201/2	IF = 20mA	-	15	-	Deg
Peak Wavelength	λp	IF = 20mA	-	465	-	nm
Dominant Wavelength	λD	IF = 20mA	465	470	475	nm

\*Tolerance of viewing angle: -10 / +5 deg.





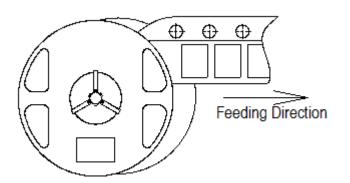
### **OPTICAL CHARACTERISTIC CURVES**





### PACKAGING SPECIFICATION

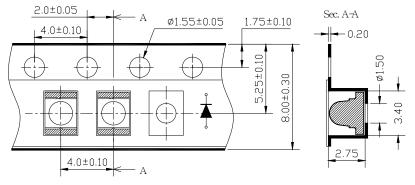
#### **Feeding Direction**



180.0±0.5

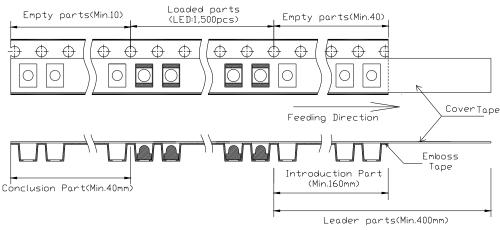
Dimensions of Reel (Unit: mm)

#### Dimensions of Tape (Unit: mm)



8.4+2

#### Arrangement of Tape



#### Notes:

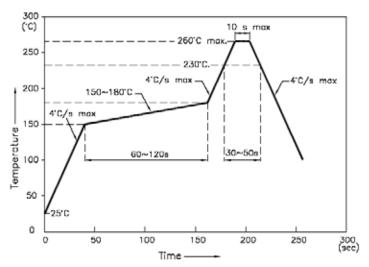
- 1. Empty component pockets are sealed with top cover tape
- 2. Maximum number of missing lamps is two
- 3. Cathode is oriented towards the tape sprocket hole in accordance with ANSI/EIA RS-481 specifications
- 4. 1,500 pcs/Reel





### SOLDERING CONDITIONS

### **REFLOW PROFILE**



#### Notes:

- 1. We recommend reflow temperature 245°C (±5°C). The maximum soldering temperature should be limited to 260°C.
- 2. Do not cause stress to epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process should be 2 times or less.
- Soldering Iron

Basic spec is  $\leq 5$  sec when 260°C. If temperature is higher, time should be shorter (+10°C $\rightarrow$ -1 sec). Power dissipation of iron should be smaller than 20W and temperature should be controllable. Surface temperature of device should be under 230°C.

- Rework
  - 1. Customer must finish rework within 5 sec under 260°C.
  - 2. The head of the iron cannot touch copper foil.
  - 3. Twin-head type is preferred

